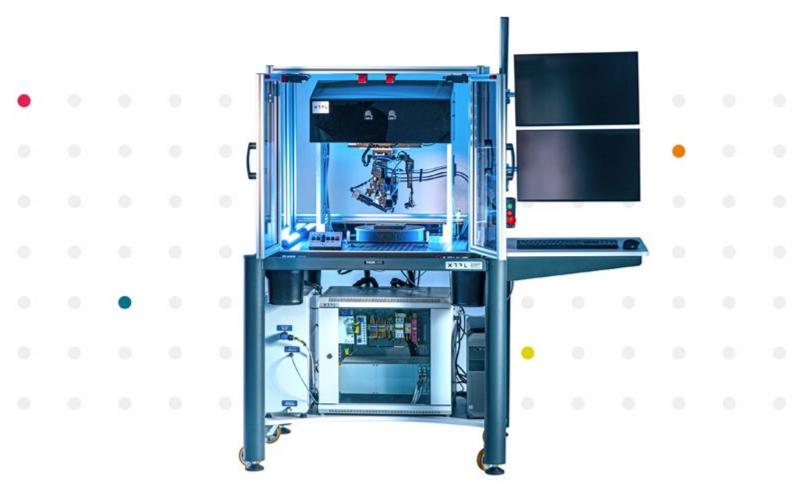
# **X T Delta** Printing System



First truly additive method for printing single micron functional structures











### **Benefits and advantages**

- Feature sizes down to submicron scale
- Wide range of material support
- Printing on heterogeneous materials and 3D topographies
- · Uniform & clean feature geometries: no overspray, high linewidth homogeneity
- Fast & easy exchange of cartridges & nozzles
- Only 0.1 ml of ink required to start printing
- Up to 100% ink utilization

### Ultra-Precise Dispensing (UPD) technology

- Ultra-high-resolution printing on various substrates
- High-viscosity materials along with small feature sizes
- High aspect ratios just after a single pass
- Wide range of printable materials: metallic nanoparticle inks and pastes, quantum dot inks, dielectrics, polymers, photoresists, organic, liquid metal alloys and more
- · Uninterrupted interconnections on highly complex topographies

### Revolutionize your industry with the power of UPD



### Semiconductors

- · High precision with submicron feature size
- A wide range of materials supported for varied semiconductor fabrication needs
- High aspect ratios, ideal for conductive power interconnections
- Quick process enhances efficiency and ensures uniform, reliable end products
- Printing on complex 3D surfaces More-than-Moore devices



- Biosensing pattern fabrication on flexible substrates, vital for wearable sensors
- Functionalized materials to prototype biosensors targeted at specific markers
- Unparalleled precision for swift biosensor prototyping
- Ability to print structures through different types
   of microchannels



### Printed Circuit Boards

- A wide variety of materials facilitating specific PCB structure creation and integration
- · High aspect ratio structures in a single pass
- Printing on complex 3D



### Flexible Hybrid Electronics

- Superior precision for Flexible Hybrid Electronics manufacturing
- Reliable 3D chip interconnections directly on vertical slopes
- Conductive and non-conductive materials for complex circuit patterns and reliable interconnections
- High aspect ratios in a single pass
- Uniform, clean geometries promote FHE device performance and Radio Frequency (RF) capabilities



### high recolution printing for OLED a

- Ultra-high resolution printing for OLED and microLED displays
- Precision ideal for interconnections, microcavity filling, and defect repair
- Dispensing of various display architecture elements, such as color conversion layers and interconnectors
- Single-step, high-precision additive process increases yield and reduces production time and costs

### Unleash the power of cutting-edge technology!







Open defect repair



Microdots dispensing



Chip interconnection on flexible substrate



Filling the microwells and TSV



High-frequency structures

## What sets technology apart and makes it the ideal choice for you?



### Prof. Norbert Fruehauf, Director of IGM at University of Stuttgart

"The XTPL's ability to directly dispense (in a mask-less approach) electrically conductive structures in the minimum feature size range of 1.5 – 10 micrometers is unique. In my view the XTPL's ultra-precise dispensing technology offers truly unique properties, which are an excellent fit to the future needs in the field of printable high-resolution and foldable OLED displays."

### Prof. Ravinder Dahiya, The Leader of the Bendable Electronics and Sustainable Technologies (BEST) Research Group at Northeastern University

\*Our research revolves around the development of high-performance printed electronics and sensing systems on large area flexible substrates. We used these printed systems to develop flexible electronic skin (eSkin) and explore its application in healthcare, wearable systems and robotics. In our projects we also use micro/nanofabrication tools and align them with processing on flexible substrates. We decided to purchase the Delta Printing System for our labs, after performing initial tests with the team at XTPL over the last several months. This appears to be a great enabling tools and we are looking forward to including it in our daily research work."

### **DPS device details**

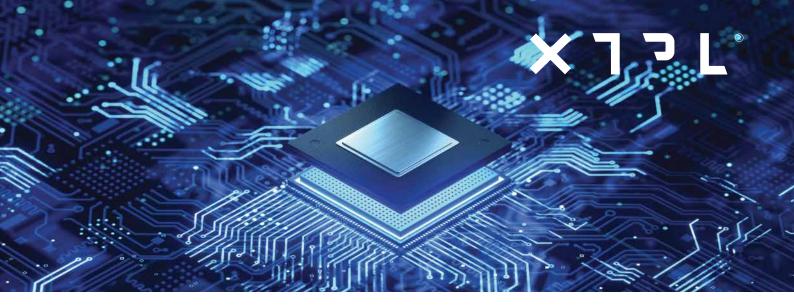
| Item  | Value  |  |
|---|--|--|
| Feature size range  | ultra-high resolution from 0.5 $\mu m$ to 1 $\mu m$          |  |
|   | high resolution from 1 µm to 10 µm                           |  |
|   | medium resolution from 10 $\mu m$ to 50 $\mu m$              |  |
| Viscosity   | from 10 to over 1 000 000 cP                                 |  |
| Substrate alignment   | 3-point levelling table with rotation error correction       |  |
| Printing area   | 200 mm × 200 mm  |  |
| Maximum printing speed  | 10 mm/s  |  |
| Process preview   | Video feedback from 2 high-resolution and 1 top view cameras |  |
| XY motor movement accuracy / repeatability                                  | 2 µm / 0.5 µm  |  |
| Z motor movement accuracy / repeatability (vertical adjustment)             | 0.5 μm / 0.5 μm  |  |
| Printer cabinet dimensions (excluding peripherals and Printing Workstation) | 1100 mm x 950 mm x 1925 mm                                   |  |

### Contact our team

### ☑ sales@xtpl.com

For any product-related inquiries, contact our team members, who are readily available to provide you with professional and comprehensive assistance.

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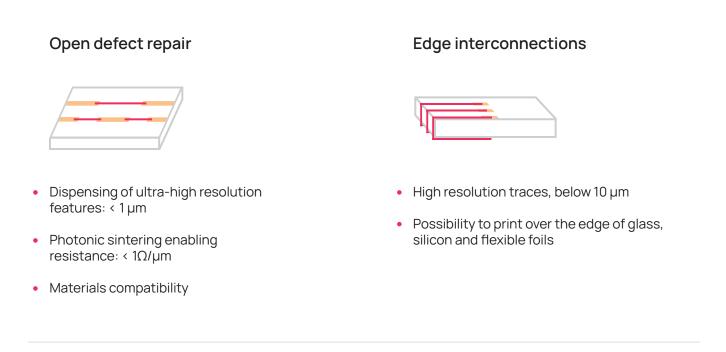


### Ultra-Precise Dispensing Technology

### XTPL. Powering the microelectronics of tomorrow.

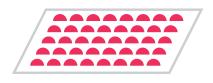
### Key features

XTPL Ultra-Precise Dispensing (UPD) technology offers an unparalleled set of features that are not available in any other additive method. These include high-resolution printing (down to submicron feature size), the ability to use high-viscosity materials (up to 1000 000 cP) and precise printing in 3D. The combination of these features makes it possible to achieve capabilities that were previously impossible with any other additive method.

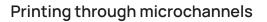


### Microdots dispensing





- Microdots printing
- Excellent height to width aspect ratio
- Capability to use conductive and non-conductive adhesives





- Printing structures across different types of microchannels
- Direct dispensing of conductive electrodes or photoresist (ex. SU-8)
- Fast and reliable solution for microfluidic, med-tech and MEMS

### 3D micro-electronics printing



- Directly on vertical step
- No ramps needed
- Reliable connection for flexible hybrid electronics and advanced IC packages

## • [ -

- Precise filling of microlavities, high aspect ratio vias, microwells
- Variety of materials like: conductives, dielectrics, photoresist, quantum dots
- Use-cases like QD color conversion, high-density TSV, RDL interconnection, sacrificial layer in MEMS fabrication

### Redistribution layer prototypying



- All printed RDL structure
- Down to 1 µm / 1 µm L/S density
- Variable materials possible to use in one system, for example metalic nanoparticle paste and high viscous polyimide

### **High-frequency structures**



- High resolution antenna on-chip
- No satelite droplets and high uniformity to prevent high frequency signal loses
  - Wire-bonding interconnection alternative

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# High-Performance Materials



### XTPL<sup>®</sup> Nanoinks Benefits

Explore XTPL's metallic nanoinks benefits — enabling swift development cycles and ensuring optimal resolution and conductivity. Our innovation propels your project forward in any field.



Up to 50% silver bulk conductivity



High content of conductive component



Superior stability

### **High-Performance Materials**



### Ag Nanoink IJ36 Conductive Silver Ink

- Stable printing for >1 month
   without clogging
- Exceeds 40% bulk Ag conductivity
- High aspect ratios with single-pass printing



### Ag Nanoink CL34 Conductive Silver Ink

- Up to 50% bulk silver conductivity
- Ideal for printing on foils for flexible electronics
- Suitable for low aspect ratio profile applications



### Ag Nanoink CL60 Conductive Silver Ink

- High-viscosity for fine, high-aspect printing
- Facilitates easy dispensing and LIFT blading
- Ensures smooth deposits
   and donor surfaces



### Ag Nanopaste CL85 Conductive Silver Paste

- High-viscosity enables
   ultra-fine, high-aspect ratio printing
- Exceptional non-clogging properties allows >1 month, 2.5 µm nozzle lifetime
- Dispenses through 1 µm nozzles for uniform thin lines
- Suitable for printing on vertical surfaces

### **Typical properties**

| Properties   | Ag Nanoink IJ36   | Ag Nanoink CL34  | Ag Nanoink CL60                             | Ag Nanoink CL85                             |
|--|-------------------|--|---|---|
| Silver content (wt. %)                                   | 34 ± 2            | 30 ± 2   | 54 - 63                                     | 82 ± 2                                      |
| Average nanoparticles size [nm] (TEM)                    | 35 - 50           | 35 - 50  | 35 - 50                                     | 35 - 50                                     |
| Shape of nanoparticles                                   | Spherical         | Spherical  | Spherical                                   | Spherical                                   |
| Electrical resistivity [μΩ · cm]*                        | 3.95              | 3.25   | 5.11  | 4.20  |
| Viscosity (25°C, shear rate = 0.2 s <sup>-1</sup> ) [cP] | 26 - 30           | 200 - 400  | 30 000 - 50 000                             | > 1 000 000                                 |
| Solvent(s)   | Glycol ether      | Glycol(s)  | Glycol(s)                                   | Glycol(s)                                   |
| Compatible printing method                               | • Inkjet printing | Aerosol printing<br>(pneumatic atomizers)<br>LIFT<br>XTPL* Ultra-Precise<br>Dispensing | LIFT     XTPL® Ultra-Precise     Dispensing | LIFT     XTPL* Ultra-Precise     Dispensing |

\*For recommended sintering conditions

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## XJJL® High-Performance Materials

Tailor-made electronic materials

## Experts in developing customized nanomaterials

By combining expertise in material engineering and additive technologies, we transform unique concepts into reality by crafting tailored electronics materials.



### Contract manufacturing based on in-depth knowledge and experience

### Materials expertise



- · Synthesis of customized nanomaterials
- · Formulation of tailor-made inks and pastes (manufactured nanomaterials, solvents and additives)
- In-depth product characterization
- · Scaling up and optimizing production

### Printing know-how



- · Acquisition of tools, development and optimization of waveforms
- Improving printing resolution and sequences on multiple substrates

### Processing proficiency



- · Screening of multiple sintering technologies
- Optimization of sintering parameters on different substrates
- · Characterization of sintered & final products

### Elevate your innovations with XTPL





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